

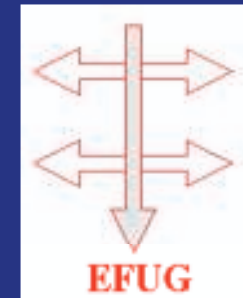
Lithography and deposition with a sub-nanometer focused helium beam (part III)

Paul Alkemade

Kavli Institute of Nanoscience

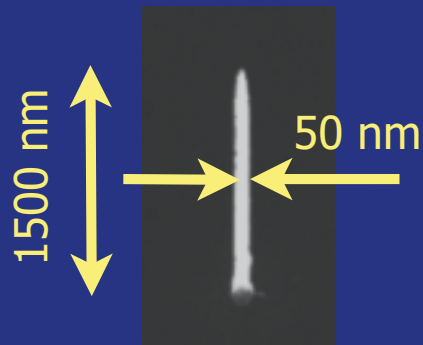
Delft University of Technology

EFUG2009 : Monday 5 October 2009
Arcachon, France



Pt-deposition in spot mode

25 keV He
(spot mode, 2 pA)
(30° tilted view)

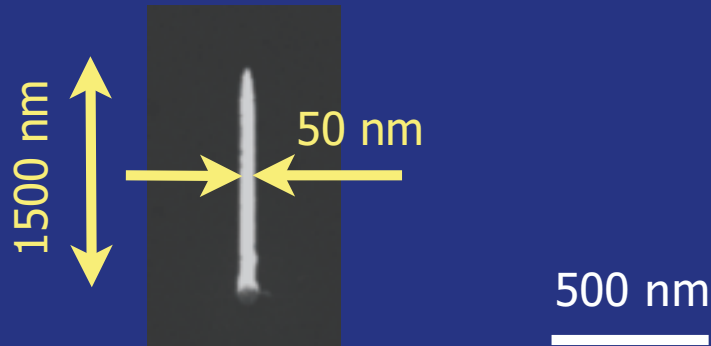


- * He-IBID is possible
- * No detrimental effects on Orion

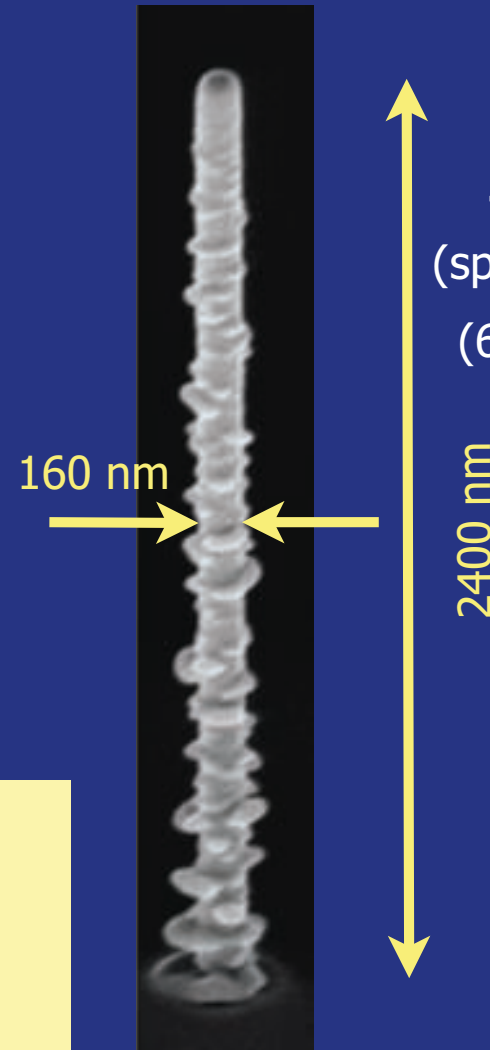
34

Comparison He - Ga IBID

25 keV He
(spot mode, 2 pA)
(30° tilted view)



30 keV Ga
(spot mode, 1 pA)
(60° tilted view)



He-IBID as compared to Ga-IBID:

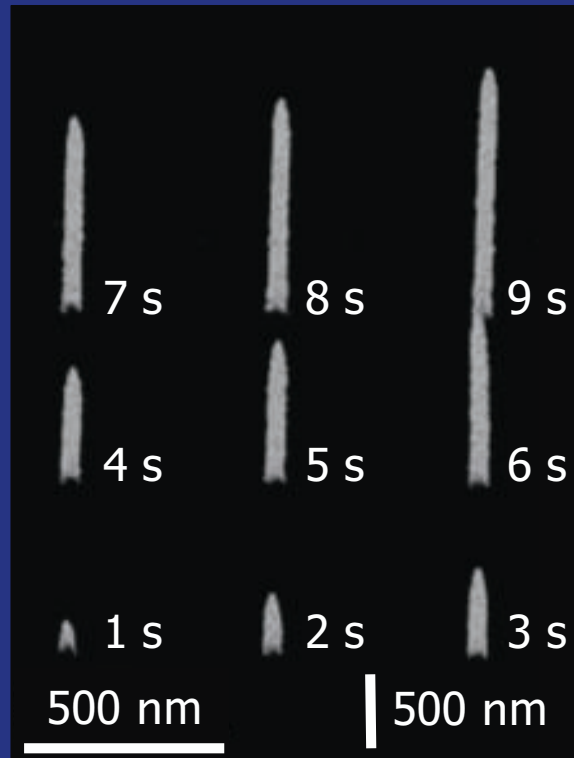
- * similar growth rate (in nm^3/s)
- * narrower pillar
- * smooth side wall

35

2.a Horizontal & vertical growth rates

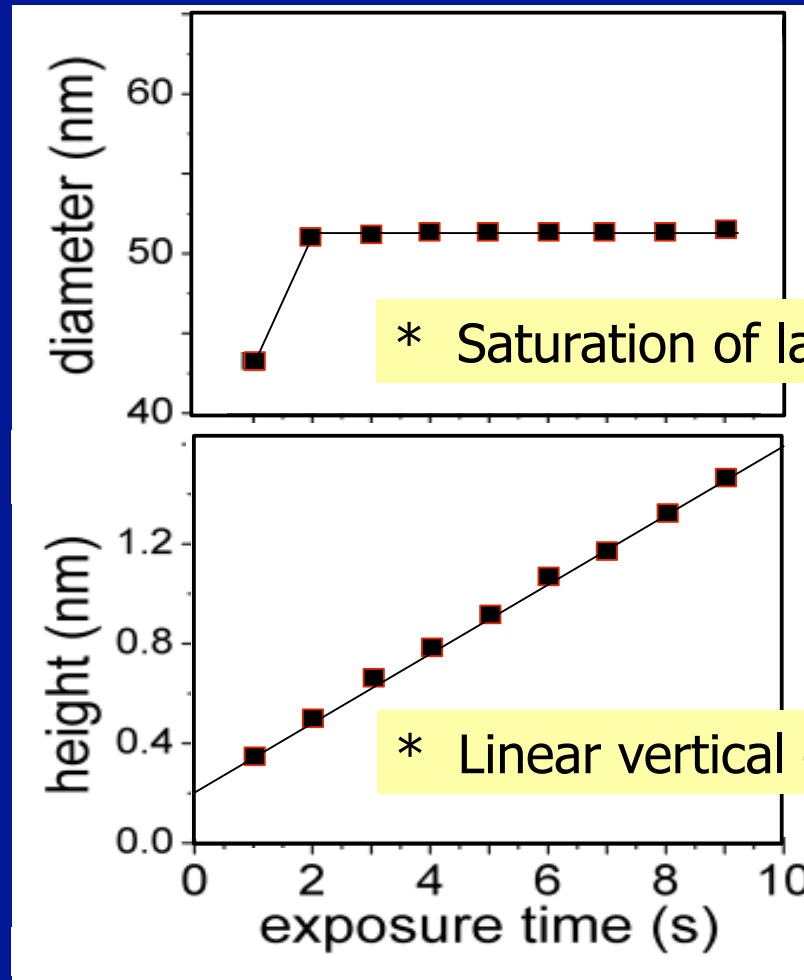
36

Pillar height & diameter vs. time



37

Pillar height & diameter vs. time

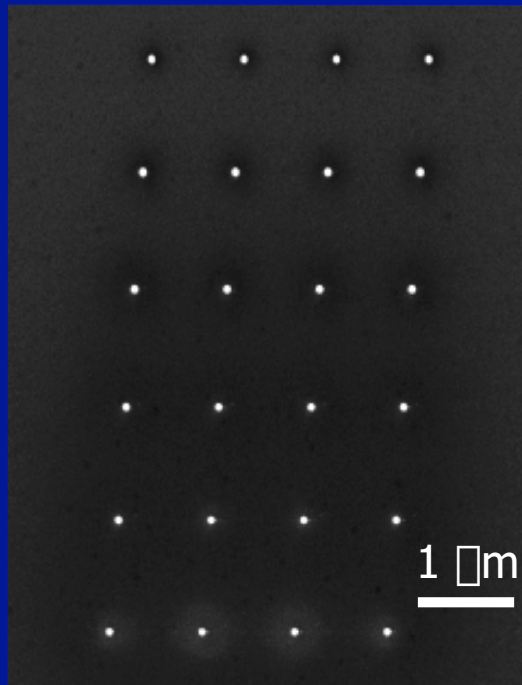


38

Variable current

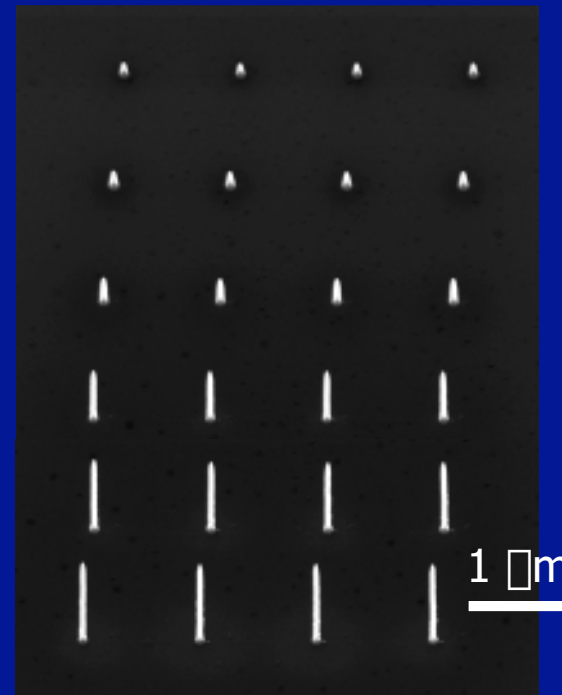
- * constant time
- * constant Pt-supply

top view



increasing current
↓

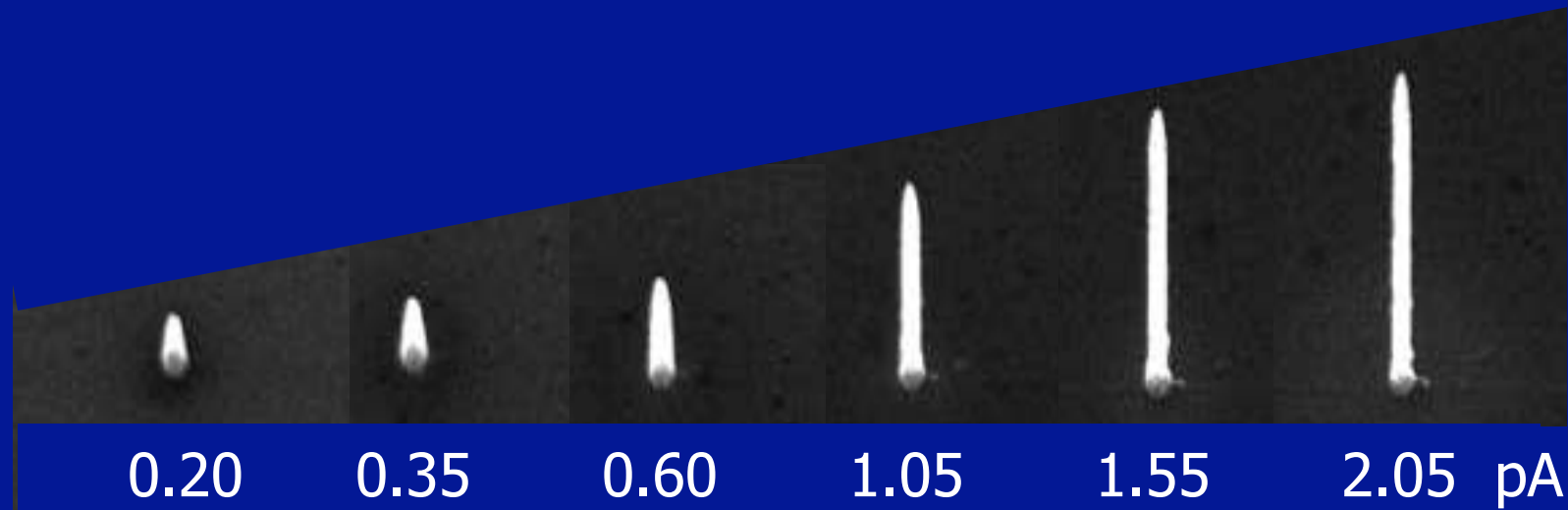
30° tilted view



Variable current

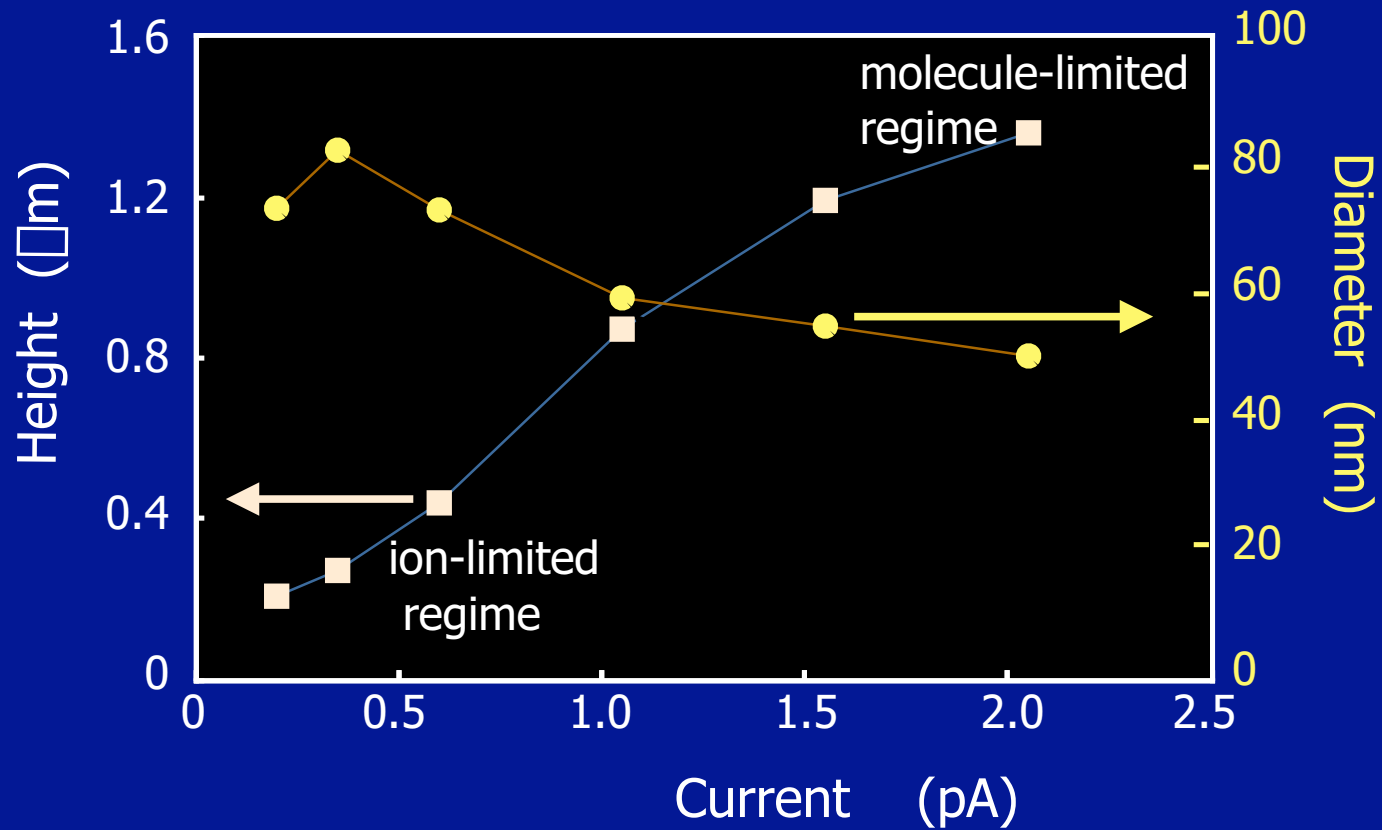
* constant time

* constant Pt-supply



40

Pillar height & diameter vs. current

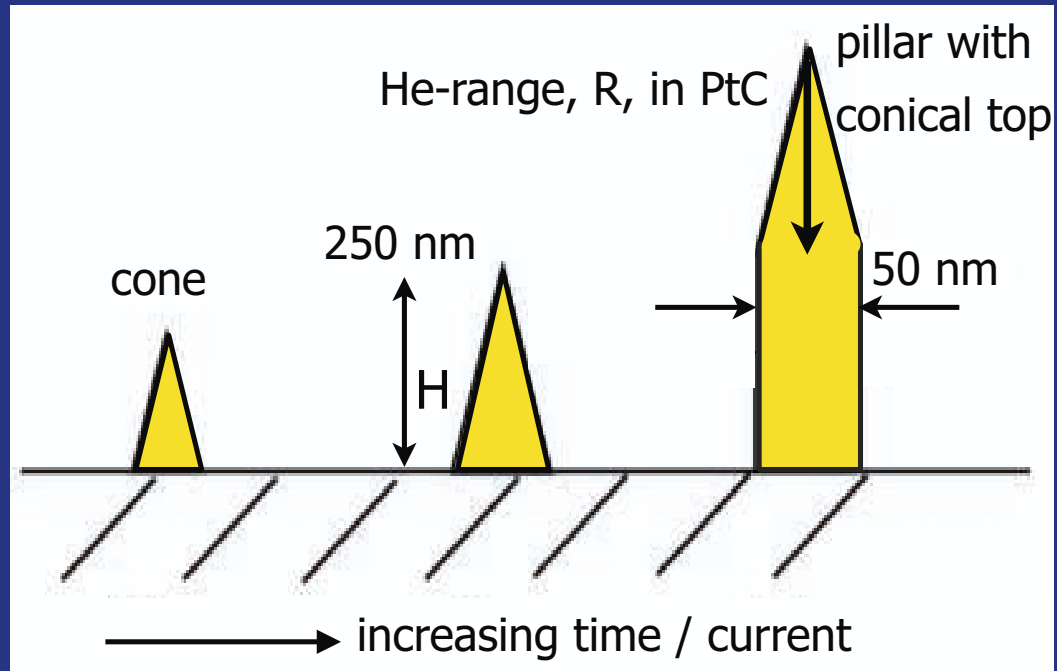


41

2c. Growth mode & growth mechanism

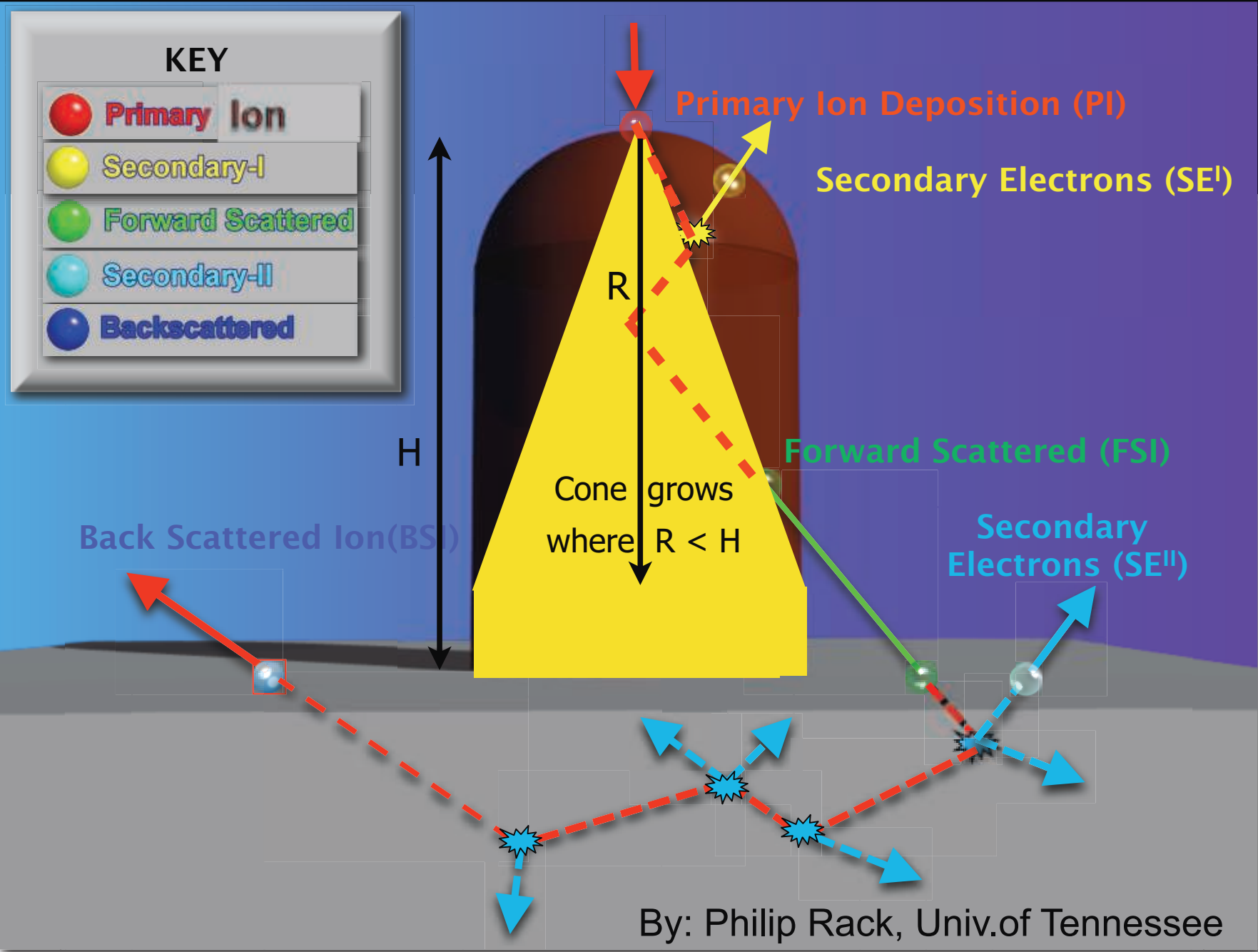
42

Pillar shape



KEY

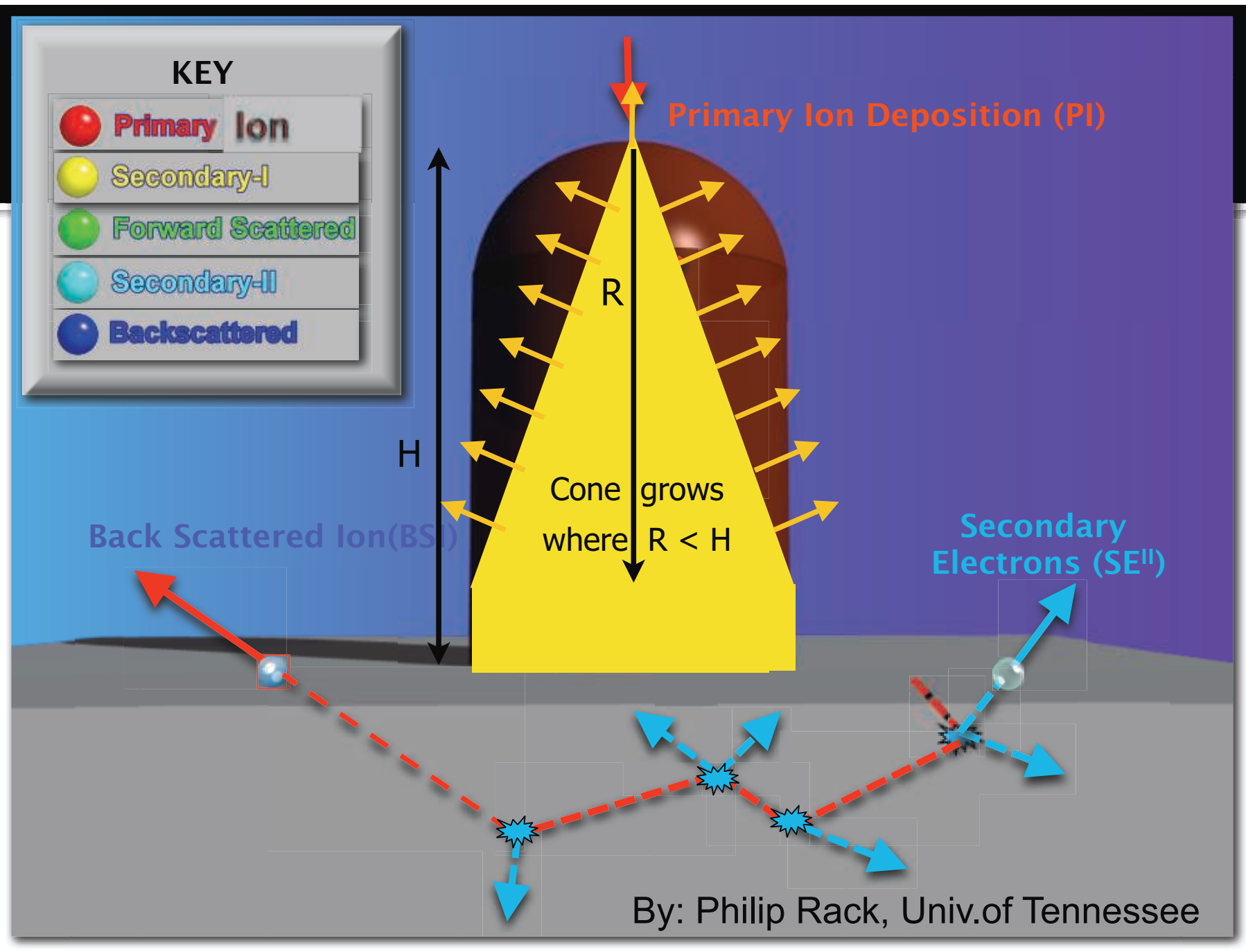
- **Primary Ion**
- **Secondary-I**
- **Forward Scattered**
- **Secondary-II**
- **Backscattered**



By: Philip Rack, Univ.of Tennessee

KEY

- Primary Ion
- Secondary-I
- Forward Scattered
- Secondary-II
- Backscattered

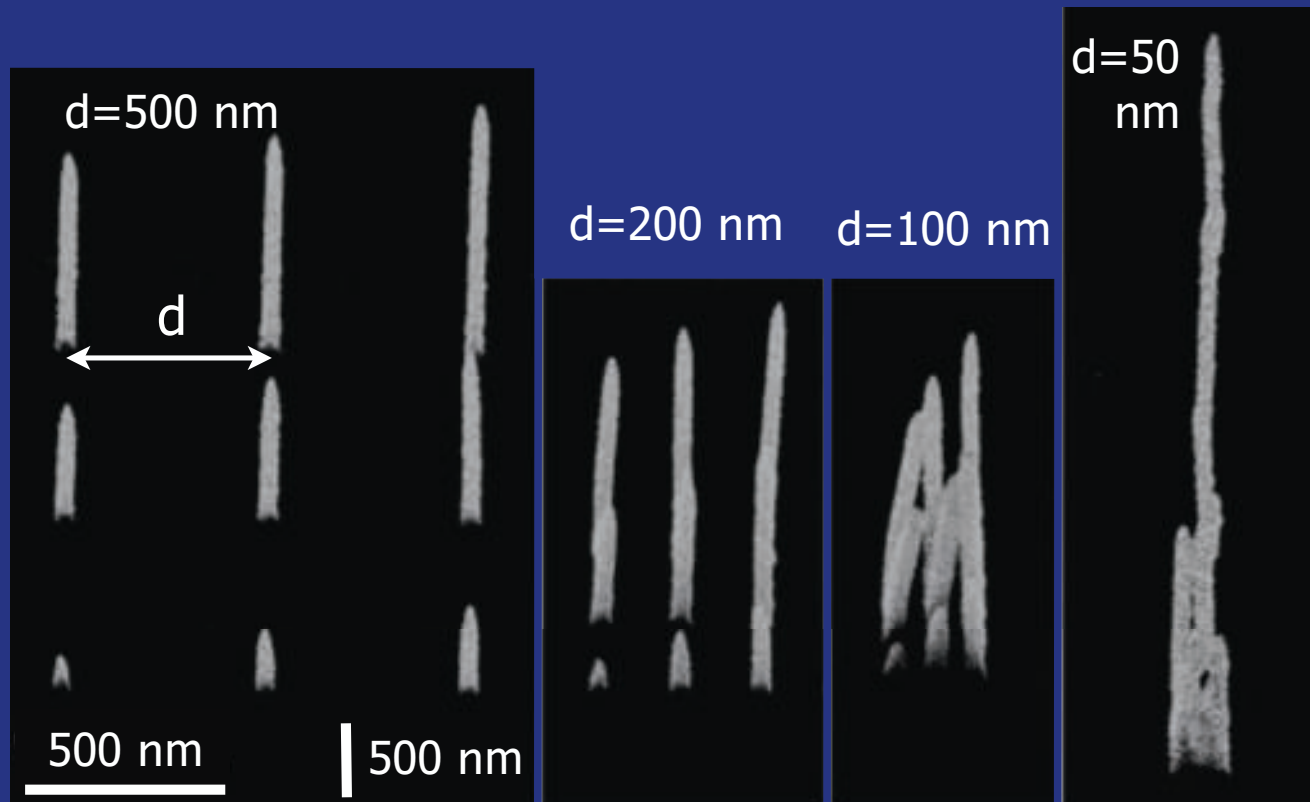


By: Philip Rack, Univ.of Tennessee

2c. Proximity effect

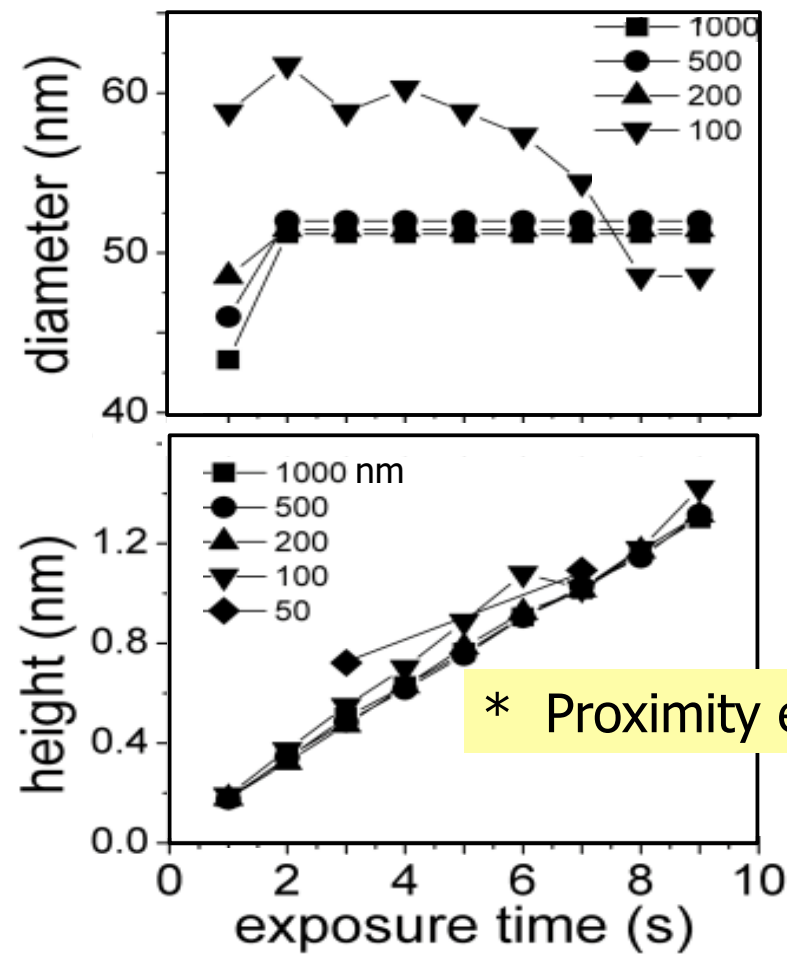
46

Proximity effect



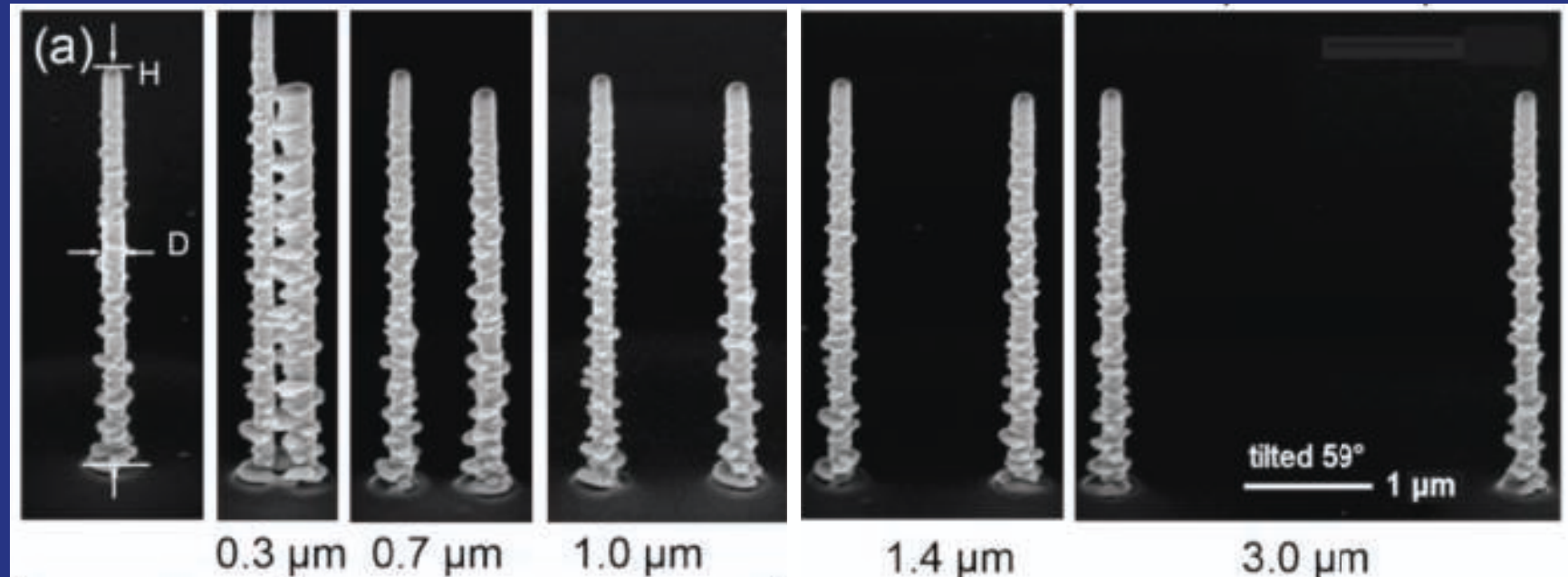
47

Proximity effect



* Proximity effect if $d < 200$ nm

Proximity effect in Ga-IBID pillars



Proximity effect:

- * one is longer
- * the other is broader

Observable if $d < \sim 2.5 \mu\text{m}$

Ping Chen et al., J.Vac.Sci.Technol. B **27** 1838 (2009)

Comparison He - Ga IBID

	He	Ga
Vertical growth rate (nm/s)	150	16
Diameter (nm)	50	160
Deposition yield (nm ³ /ion)	7.9×10^{-2}	4.5×10^{-2}
Proximity distance (nm)	200	2500

He-IBID looks better than Ga-IBID

Helium lithography vs. electron lithography

1. **HSQ and PMMA: 4 - 40x as sensitive**
2. **Comparable minimal feature size (~ 6 nm)**
3. **Low proximity effect**
4. **Maximal current 2 pA (200 pA for EBL)**
5. **Non-optimized beam conditions**
6. **Beam damage to specimen**

Helium IBID vs. gallium IBID

1. **Comparable sensitivity (for Pt depo)**
2. **3x better minimal feature size**
3. **Minimal sputtering (100x lower)**
4. **Smoother surfaces ; less proximity effects**
5. **Lower Pt content**
6. **Lower beam current**

Conclusions (helium beam lithography)

- 1. HeBL good candidate:
for small-feature & high-density structures**
 - * 6 nm minimal feature size
 - * 14 nm pitch
- 2. Room for instrumental improvements**
beam current & beam shape
- 3. Exposure is related to ion's energy loss**

Conclusions (ion beam induced deposition)

1. He-IBID is feasible

* relative high yield

* low minimal feature size (50 nm / 12 nm)

2. Room for instrumental improvements

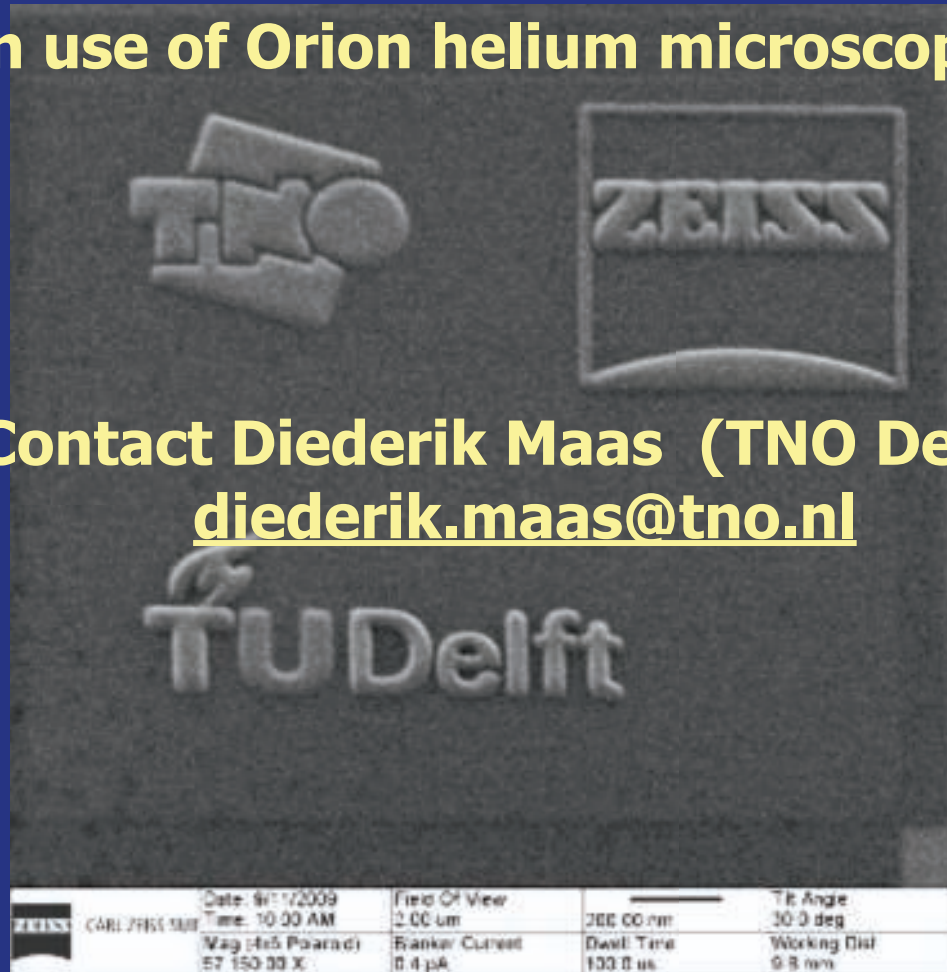
beam current & beam shape

3. Deposition is caused to secondary electron emission

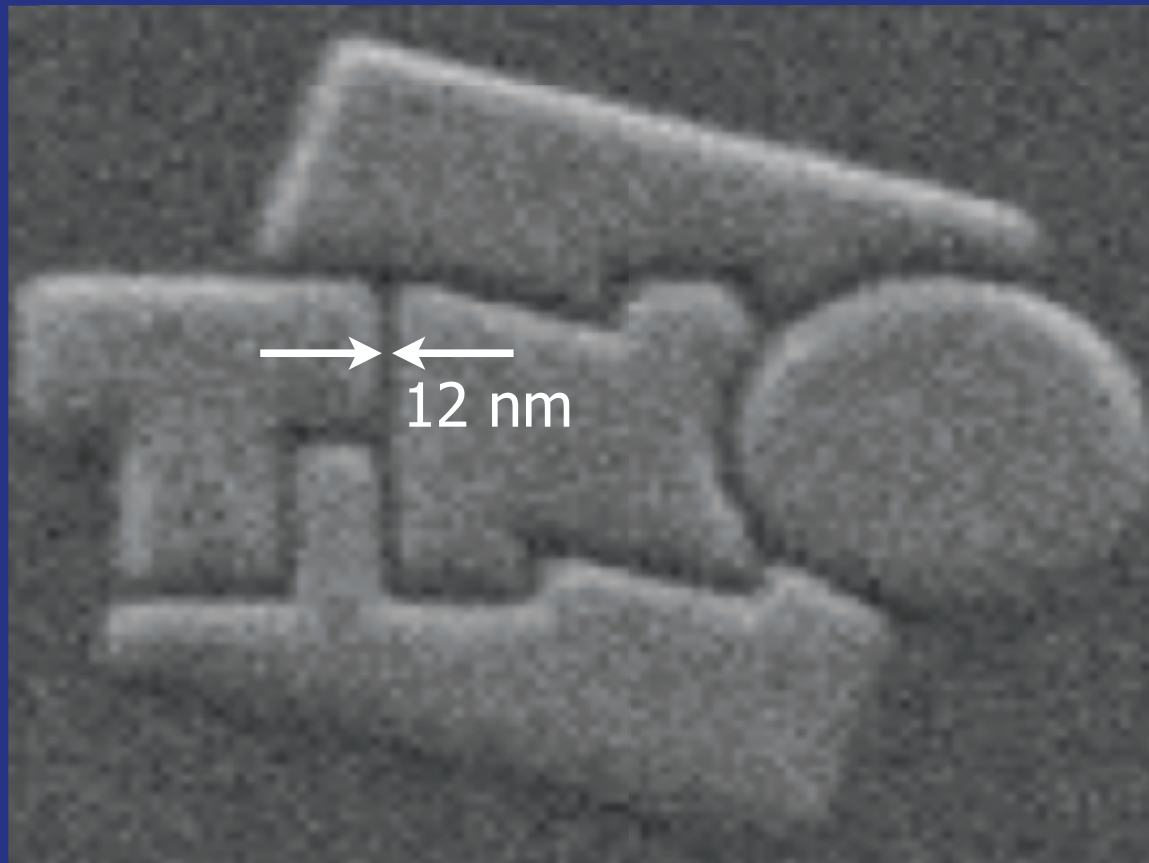
4. Deposition & observation in one instrument

Interested in use of Orion helium microscope in Delft?

Contact Diederik Maas (TNO Delft):
diederik.maas@tno.nl



55



Thank you